Serial No.: AL190502011-00



PRODUCT TYPE Quartz Crystal HSX321SK NOMINAL FREQUENCY 14.745600MHz H.ELE. SAMPLE O/N EOS-J40433-11 H.ELE. P/N X3Z01474ADK1H-U **RELEASE DATE** 2019/05/02 **VERSION** 00 **MSL** Level 1 **☑** Pb free **☑** RoHS Compliant **GREEN PRODUCT ☑** HF-Halogen free **☑** REACH Compliant **CUSTOMER P/N APPLICATION & MODEL** APPROVED BY CUSTOMER (DATE)

Harmony Electronics Corp.	
F. S. TSAI C. C. HOU U. F. CHEN (APPROVE) (CHECK) (PREPARE)	Country of Origin: Taiwan Factory Thailand Factory China Factory

HARMONY ELECTRONICS CORPRATION

KAOHSIUNG TAIPEI THAILAND SHENZHEN DONGGUAN

TEL: 886-2-26588883 ______: contactus@hele.com.tw



REV. No.	DATE	REASON	REVISE CONTENTS
0	2019/05/02	New	

HARMONY ELECTRONICS CORPRATION

Kaohsiung	TAIPEI	THAILAND	SHENZHEN	Dongguan
TEL: 886-2-26	588883		Email: contactus@h	ele.com.tw



Contents

ITEM	PAGE
1. QUARTZ CRYSTAL UNIT SPECIFICATION	3
2. DIMENSIONS	4
3. MARKING	4
4. INSIDE STRUCTURE	5
5. HANDLING SUGGESTIONS	5-6
6. EMBOSS CARRIER TAPE&REEL	6-7
7. PACKAGE	7-8
8. MECHANICAL PERFORMANCE	8-9
9. ENVIRONMENTAL PERFORMANCE	9
10. APPENDIX	

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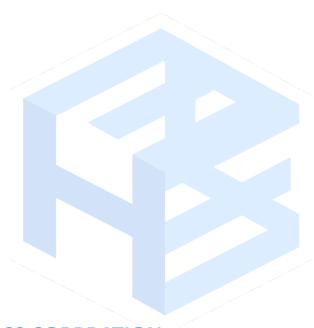
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1. QUARTZ CRYSTAL UNIT SPECIFICATION

	Electrical Spec.]	
Items	Min	Туре	Max	Unit	Notes
1. Frequency (FL)		14.745600)	MHz	
2. Mode of oscillation:	F	undament	al		
3. Frequency tolerance	-20		+20	ppm	at 25°C±3°C
4. Equivalent resistance (RR)			80	Ω	SERIES
5. Storage temperature range	-55		+125	°C	
6. Operable temperature range	-40		+85	°C	
7. Temperature stability	-20		+20	Ppm	-40°C ~ +85°C
8. Loading capacitance (CL)		20.0		pF	
9. Drive level (DL)		10	100	μW	
10. Shunt Capacitance (CO)			2.0	pF	
11. Insulation resistance	500			МΩ	at DC 100V
12. Aging:	-3		+3	ppm/Year	
13. Circuit:	Measu	red in HP/	E5100A,S	&A 250B	

Note: Storage Temperature is only for the product itself.



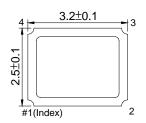
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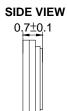
Kaohsiung Taipei Thailand Shenzhen Dongguan

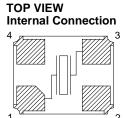


2. DIMENSION

TOP VIEW

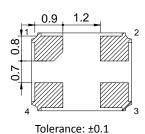






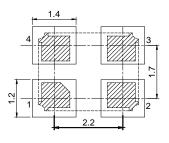
Pin Connections						
#1	Crystal					
#2	GND/Lid					
#3	Crystal					
#4	GND/Lid					
#2,#4 GND(connection Cover)						

BOTTOM VIEW



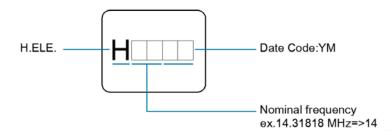
Unit: mm

TOP VIEW Land Pattern Layout



* Note: The Index mark was defined by the BASE suppliers.

3. MARKING



Note:

- 1. Laser marking.
- 2. Date Code:

V. V	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019
Y=Year	2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	0	1	2	3	4	5	6	7	8	9

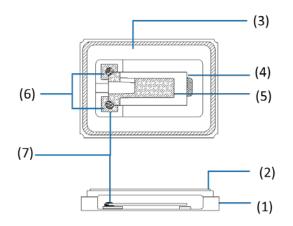
M=Month	Jan.	Feb.	Mar.	Apr.	May.	Jun.	Jul.	Aug.	Sep.	Oct.	Nov.	Dec.
Code	Α	В	С	D	E	F	G	Н	J	K	L	М

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4. INSIDE STRUCTURE



Reference drawing

No.	Component	Material	Note						
(1)	Base	Ceramic	Al_2O_3						
(2)	Lid	Metal	Fe- Ni –Co Ni Plating						
(3)	Kovar	Metal	Fe- Ni -Co						
(4)	Crystal Blank	Quartz	SiO₂ Rectangular At-Cut						
(5)	Electrode	Metal	-						
(6)	PAD	Metal	W Ni Plating Au Plating						
(7)	Connective Adhesive	Silver Powder	Ag						

※The use prohibition chemistry substance of Table 1 of DHE-0204-1 (HE-QA-24) is not included in this item.

5. HANDLING SUGGESTION

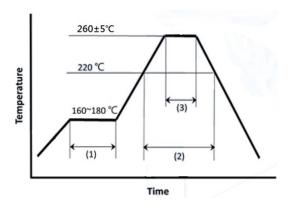
■ Reflow Condition

Please stay with our proposed reflow condition and do soldering within 2 times.

(1)	Preheat	160~180deg.C 120 sec.
(2)	Primary heat	>=220 deg.C 100±20 sec.
(3)	Peak	260±5 deg.C 10 sec. Max.

■ Manual Solder iron (Example)

Bit temp.: 350°C max., Time: 3sec max., Each terminal only should be soldered once.



■ Mounting Conditions

Our products are suitable for most automated SMT processes. However, we strongly advise all our customers to conduct SMT sampling prior to mass production in order to make sure production processes will not affect the properties and specifications of our product. Seal welding and mounting procedures involving the use of ultra-sonic processes are not recommended and will affect and/or damage the internal properties of our product. Excessive shock during the mounting process will also affect the product and we strongly recommend setting SMT conditions to minimize such conditions.

If a possibility of the PCB being warped exists we strongly advise to ensure the degree of warping will not affect the product.

Please also ensure the operating characteristics and or soldering conditions are all within the specifications of use for our product.

Ultimately the worst case scenario of all the above will lead to cases of non-oscillation but other negative effects are also likely should our products be used in an inappropriate way. Please note such cases of misuse and its related quality issues are not included in our product warranty.

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■ Cleansing Conditions

General cleaning solutions may be used to clean our products but we always recommend testing to be performed prior to mass production processes. Ultrasonic cleaning procedures are not recommended and we strongly advise other forms of cleansing to be evaluated first. Unsuitable cleansing may lead to a number of negative effects such as damage to the product surface, discoloration of the product, corrosion of the package, package contamination, illegible marking, etc. Please note cases of unadvised treatment and its related quality issues are not included in our product warranty.

■ Storage Conditions

Please ensure our products are preserved appropriately in their original packaging. Irregular environmental instances of moisture will affect our product's stability and may cause problems such as frequency instability, soldering ability and conditions, package defects, and other problems. It is essential to keep our products in a clean dust-free environment out of direct sunlight.

Our products' storage conditions should at least meet the following condition:

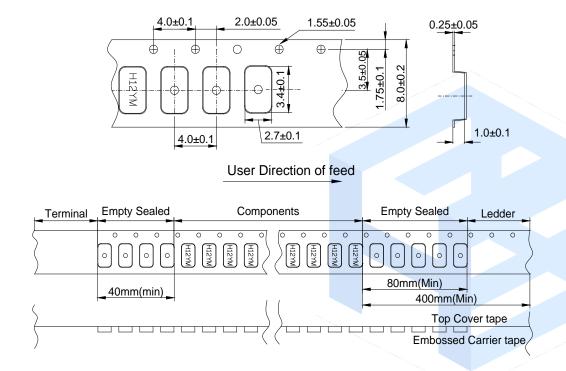
Environmental Temperature: + 40 degrees Celsius Maximum

Relative Humidity: 80% Maximum

Please note storage instances which do not conform to our guidelines and the related quality issues produced as an outcome are not included in our product warranty.

6. EMBOSS CARRIER TAPE AND REEL

■ Carrier Tape

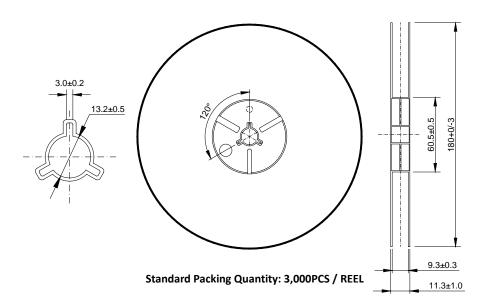


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■ Reel



■ Material of The Tape

Таре	Material
Carrier tape	PS Conductive
Top tape	PET

■ Joint of tape

The carrier-tape and top cover-tape should not be jointed.

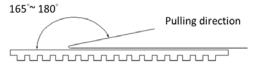
■ Release strength of cover tape

The force should be controlled between 0.1N to 0.7N under following condition.

Pulling direction: 165° to 180°

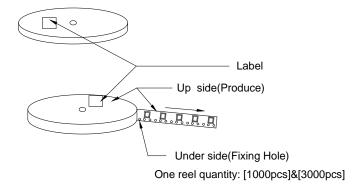
Speed: 300mm/min.

Otherwise unless specified.



Other standards shall be based on JIS C 0806-1990.

7. PACKAGE

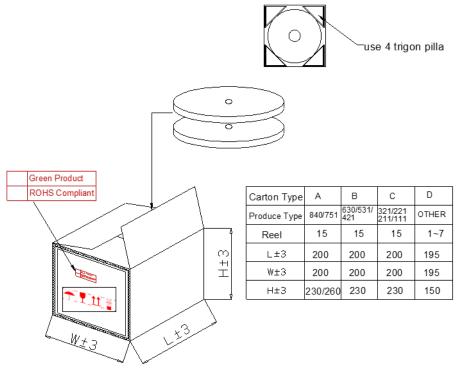




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- ①Top and bottom with 2.3cm thickness foam-rubber cushion for protection.
- ②Carton's Q'TY:1~15 pcs.
- ③Carton Type=A,B,C use 4 trigon pillar to fasten the Reel.
- 4Need to add 3 pages dry agent in each outer box.

8. MECHANICAL PERFORMANCE

	ltem	Test M	Specifications Code			
1	Shock	Dropping from 120 cm height 3 tim Refer to: JIS C 60068-2-32	Α			
2	Vibration	Frequency 10-55Hz, Sine Wave full 3 axes, 2 cycles and duration of 2 h Refer to: JIS C 60068-2-6/ MIL-HDB	A			
3	Leakage Test	Leak Rate 1.0x10 ⁻⁹ Pa-m³/sec. Max. detector. Refer to: JIS C 60068-	1			
4	Solder ability	After applying ROSIN Flux, dipping for 3 ±0.5 sec. Refer to: JIS C 60068-2-20/ JIS C 60				
5	Bending Strength	Mount a sample on board. Apply Pressure to the center of board until it is bent to 3 mm and hold for 5 ±1 sec. Pressure speed: 0.5 mm/sec. Refer to: EIAJ ET-7403/ JIS C 60068-2-21	Pressure rod 20 R230 Board 45± 2 45± 2	A		

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6	Adhesion	Mount a sample on the circuit board. Apply pressure vertically to the side of specimen attached to the circuit board with the pressure jig. Pressure: 5N for 10±1 sec. Refer to: EIAJ ET-7403 JIS C 60068-2-21	Scratch tool R0.5 Chip Cross section	А
7	Body strength	Apply pressure to the center of body with the R0.5 pressure jig. pressure:10N for 10±1sec Refer to: EIAJ ET-7403 JIS C 60068-2-21	Pressure rod R0.5 Chip L L W	А

9. ENVIRONMENT PERFORMANCE

Item		Test Methods	Specifications Code
1	Resistance of Soldering Heat	Performing as the following reflow: Refer to: JIS C 60068-2-58 >= 220 °C 160°-180 °C 100±20s	А
2	Humidity	Temperature $60^{\circ}\text{C}\pm2^{\circ}\text{C}$, RH $90^{\sim}95\%$, duration of 240 hours. Back to room temperature first, then check the component after $1^{\sim}2$ hours. Refer to: JIS C $60068-2-3$	А
3	Storage in Low Temperature	-40deg.C ±2deg.C, duration of 240 hours. Back to the room temperature first, then check the component after 1~2 hours. Refer to: JIS C 60068-2-1	А
4	Storage in High Temperature	+85deg.C ±2deg.C, duration of 240 hours. Back to the room temperature first, then check the component after 1~2 hours. Refer to: JIS C 60068-2-2	A
5	Thermal shock	-55deg.C ±2deg.C (30min) ↔ +125deg.C ±2deg.C (30min) 25 cycles. And Temperature Increasing/reducing time ≤ 3mins. Back to the room temperature first, then check the component after 1~2 hours. Refer to: JIS C 0025	A

Specifications code	Specifications		
Α	FREQ. DRIFT: ±5 ppm Max, RESISTANCE DRIFT: ±15% or 2Ω		
В	More than 90% of lead shall be covered by new solder.		

HARMONY ELECTRONICS CORPRATION

KAOHSIUNG TAIPEI THAILAND SHENZHEN DONGGUAN

FACTORY LOCATION HEAD OFFICE/TAIWAN FACTORY

NO.39, HUADONG RD., DALIAO DIST., DAFA INDUSTRIAL PARK, KAOHSIUNG CITY 831.

CHINA FACTORY

SHEN ZHEN

JU YUAN INDUSTRIAL PARK, QIAO TANG ROAD, TANG WEI COMMUNITY, FUYONG, BAOAN DISTRICT, SHEN ZHEN CITY (Post Code:518103).

DONGGUAN

BUILDING A1, HUAZHI INDUSTRIAL PARK, NO.38, JINGFU EAST ROAD, DALANG TOWN, DONGGUAN CITY.

THAILAND FACTORY

66MOO 5, KAONGU-BEOKPRAI RD., T.BEOKPRAI, A. BANPONG, RATCHABURI PROVINCE 70110.

SERVICE CENTER TAIPEI OFFICE

2F., NO.409, SEC.2, TIDING BLVD., NEIHU DISTRICT, TAIPEI CITY 114, TAIWAN TEL: 886-2-26588883 FAX: 886-2-26588683

CONTACT INFORMATION

E-MAIL: contactus@hele.com.tw



单击下面可查看定价,库存,交付和生命周期等信息

>>HELE(加高)